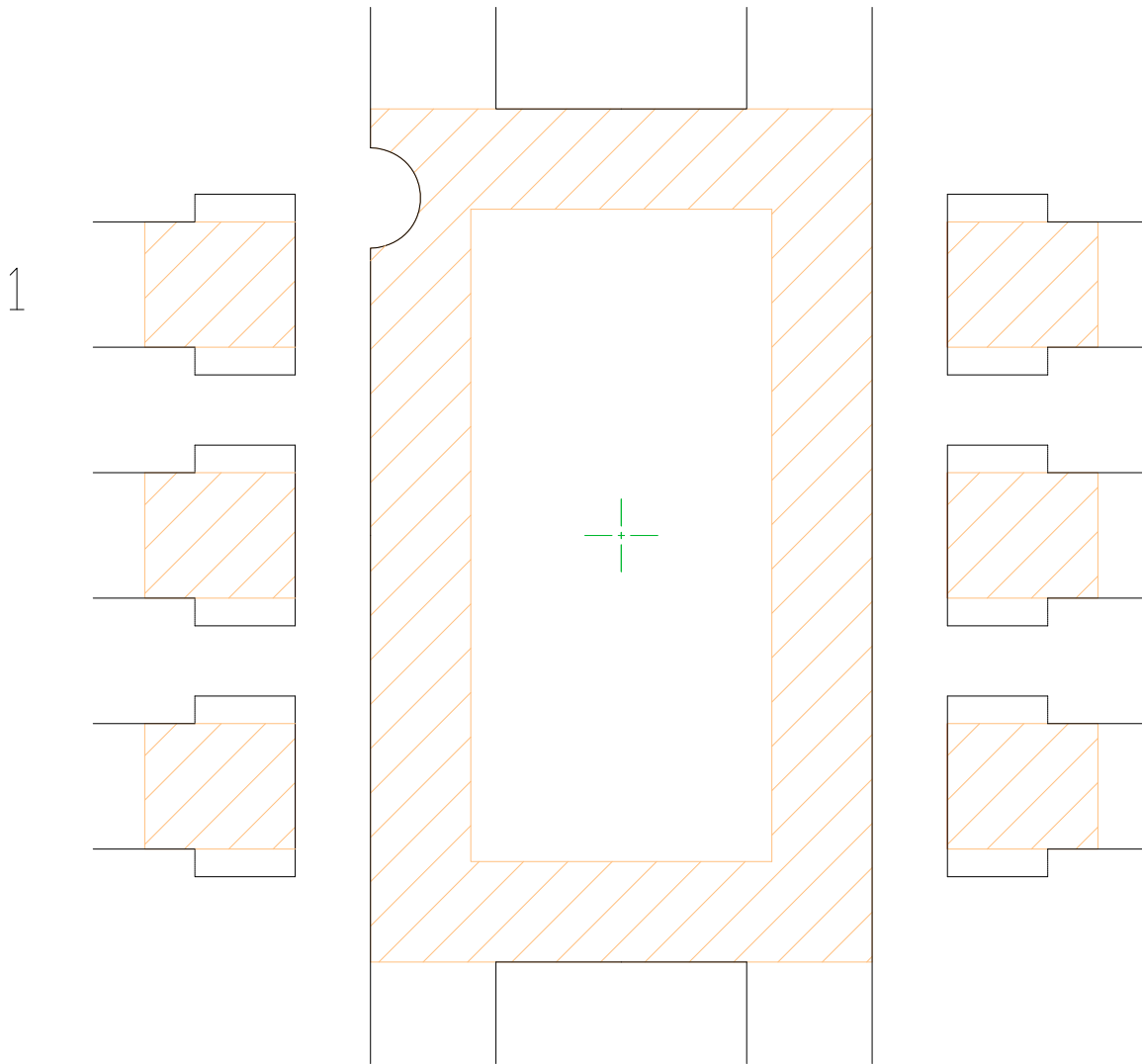



REVISIONS		
REV	DESCRIPTION	DATE
C	UPDATE PLATING SPEC	8-21-2017



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 <a href="http://www.promex-ind.com">www.promex-ind.com</a>
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 1.00 x 1.70 mm	
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 0.80 x 1.45 mm	TITLE DFN 6L 2x2 mm 0.50 PITCH BOND SHELL
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	LEADFRAME P/N: 235-00068
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	DO NOT SCALE
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	
		FILE NAME 6L-DFN-2X2-50P-BD.DWG
		SHEET 1 OF 1
		REV 00